

# Inductorless –2x Boost/Buck Regulator

### **FEATURES**

- Input Range 2.5V to 5.5V
- Regulated Output Options from -3.0 to -5.0V
- Output Current 20 mA (max)
- 200 KHz Internal Oscillator Frequency
- External Synchronizing Clock Input
- Logic Level Shutdown ....... 1µA (max) Supply Current
- 8-Pin MSOP Package

### **TYPICAL APPLICATIONS**

- Cellular Phones
- Battery Powered/Portable Equipment

### TYPICAL APPLICATION



## **GENERAL DESCRIPTION**

The TC1142 generates a regulated negative voltage from –3V to –5V at 20 mA from an input of 2.5V to 5.5V, using only three external capacitors. Other boost/buck switching regulators must use an inductor, which is larger and radiates EMI. An internal voltage comparator inhibits the charge pump when V<sub>OUT</sub> is more negative than the regulated value (per the ordering option). The values of flying capacitors C1 and C2 are chosen to be less than C<sub>OUT</sub> in order to reduce the ripple generated from regulating V<sub>OUT</sub> in this manner. The TC1142 also can be used as a –1x buck regulator by omitting C2, and connecting the C2-pin to V<sub>OUT</sub>.

The part goes into shutdown when the CCLK input is driven low. When in shutdown mode, the part draws a maximum of 1  $\mu$ A. When CCLK is pulled high, the part runs from the internal 200 KHz oscillator. The device may be run with an external clock, provided the frequency is greater than 3 KHz and less than 500 KHz.

The TC1142 comes in a space-saving MSOP package.

## **ORDERING INFORMATION**

Package	Temp. Range
8-Pin MSOP	–40°C to 85°C
8-Pin MSOP	–40°C to 85°C
8-Pin MSOP	–40°C to 85°C
	Package8-Pin MSOP8-Pin MSOP8-Pin MSOP

Note: Contact factory for availability of -3.5 and -4.5V options.

### **PIN CONFIGURATION**



## **ABSOLUTE MAXIMUM RATINGS\***

Supply Voltage (VIN) with COUT Connected	.6.5V
CCLK Voltage – 0.3V to (V <sup>+</sup> +	0.3V)
Operating Temperature Range	
TC1142EUA – 40°C to +	-85°C
Storage Temperature Range 65°C to +1	60°C
Lead Temperature (Soldering, 10 sec)+3	300°C
Power Dissipation	0 mW

\*Static-sensitive device. Unused devices must be stored in conductive material. Protect devices from static discharge and static fields. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to Absolute Maximum Rating Conditions for extended periods may affect device reliability.

**ELECTRICAL CHARACTERISTICS:** ( $R_L = \infty$ ,  $V_{IN} = 3.2V$ , Mode = -2X,  $C_1 = C_2 = 0.47 \mu F$  (Note 1), CCLK =  $V_{IH}$ ,  $C_{OUT} = 4.7 \mu F$ , For  $V_R = 3V$ ,  $V_{IN} = 3.5V$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
VIN	Supply Voltage		2.5	_	5.5	V
V <sub>OUT</sub>	Output Voltage	I <sub>L</sub> = 0 mA (Note 2)	$-(V_{R} + 0.2)$	$-V_R$	–(V <sub>R</sub> – 0.2)	V
V <sub>p-p</sub>	Output Ripple	I <sub>L</sub> = 10 mA	—	100	—	mV
I <sub>SUPPLY</sub>	Supply Current		—	200	400	μA
I <sub>SUPPLY1</sub>		CCLK = 0V	—	0.1	1	μA
ROUTCL	Closed-Loop Output Resistance		—	2	6	Ω
R <sub>OUT</sub>	Open-Loop Output Resistance	(Note 3)	—	30	—	Ω
fosc	Internal Oscillator Frequency		150	200	275	KHz
f <sub>CCLK</sub>	External Clock Frequency, Typical	(Note 4)	3	—	500	KHz
P <sub>EFF</sub>	Power Efficiency	$I_L = 10 \text{ mA}, V_R = 5 \text{V}; \text{ (See Equation 5)}$	70	76	—	%
VIH	CCLK Input High Threshold		2.2	—	—	V
V <sub>IL</sub>	CCLK Input Low Threshold				1.0	V

Note: 1. Assume C1 and C2 have an ESR of  $1\Omega$ .

2.  $V_R$  is the voltage output specified in the ordering option

3. Measured in –1X Mode. For  $V_{\text{R}}$  = 3V,  $V_{\text{IN}}$  = 2.5V

4. CCLK is driven with an external clock. Minimum frequency =  $1/2t_0$  at 50% duty cycle, where  $t_0$  is the counter timeout period.

### **PIN DESCRIPTION**

Pin No. (SOT-23A-5)	Symbol	Description	
1	Vout	Regulated negative output voltage.	
2	C2-	Negative terminal of flying capacitor C2.	
3	C2+	Positive terminal of flying capacitor C2.	
4	C1-	Negative terminal of flying capacitor C1.	
5	GND	Power supply ground.	
6	C1+	Positive terminal of flying capacitor C1.	
7	V <sub>IN</sub>	Power supply positive voltage input (2.5V to 5.5V).	
8	CCLK	Clock control input: If low, the TC1142 is in Shutdown mode (1 $\mu$ A, max). If high, the TC1142 runs off the internal oscillator (200 KHz, typ.). CCLK can be overridden by an external oscillator from 3 KHz to 500 KHz.	

### DETAILED DESCRIPTION

The TC1142 inductorless –2x boost/buck regulator is an inverting charge pump that uses a pulse-frequency modulation (PFM) control scheme to produce a regulated negative output voltage, –V<sub>R</sub>, between –3V and –5V (depending on the output voltage option) at 20 mA maximum load. Output voltage regulation is achieved by gating ON the clock to the charge pump for a single half-clock period whenever the output is more positive than V<sub>R</sub>, and gating it OFF when the output is more negative than –V<sub>R</sub>. The resulting PFM of the clock applied to the charge pump has a high frequency spectral content consisting only of clock harmonics. When using an external clock, the transient noise is then synchronized to the clock and is easier to filter in sensitive applications.

The TC1142 also can be used as a -1x boost/buck regulator by omitting the C2 capacitor and connecting the C2– pin to V<sub>OUT</sub>.

The PFM control scheme minimizes supply current at small loads and permits the use of low value flying capacitors, which saves on printed circuit board space and cost. Due to the TC1142's doubling and inverting charge pump mechanism, the output voltage is limited to  $-2V_{IN}$ . To produce a -5V regulated output, for example, a minimum input voltage of 2.5V is required at  $V_{IN}$ .

The CCLK pin of the TC1142 has three functions: It can select the internal 200 KHz oscillator (when held HIGH), put the TC1142 into shutdown (when held LOW), or provide an external clock input. To achieve this functionality, an internal counter is reset by any positive transition at the CCLK pin, but will time out in typically 160 µsec (i.e. a frequency higher than about 3 KHz). If the counter times out following the last positive transition, then the internal clock will be gated through to the charge pump if CCLK is HIGH, or the device will enter shutdown mode if it is LOW. To enter shutdown, CCLK must be LOW and the counter must have timed out. These timing diagrams are shown in Figure 4.

A functional circuit diagram of the TC1142 is shown in Figure 1. The output voltage  $V_{OUT}$  is compared to an on-chip reference voltage, and the comparator output is used to gate the charge pump clock. The charge pump is a negative voltage doubler and has two phases of operation which are further illustrated in Figures 2 and 3. In phase 1, shown in Figure 2, the flying capacitor C1 charges the flying capacitor C2 while the device load is totally serviced by the charge stored on the reservoir capacitor C0<sub>UT</sub>. In phase 2, shown in Figure 3, the capacitor C1 is recharged to  $V_{IN}$  while the capacitor C2 transfers its charge to the reservoir capacitor  $C_{OUT}$ .

In normal operation, the TC1142 charge pump stays in phase 2 and only switches to phase 1 as required to maintain output voltage regulation.



Figure 1. Functional Circuit Diagram



Figure 2. TC1142 Phase 1



(b) The equivalent circuit of the discharging phase of operation.

Figure 3. TC1142 Phase 2

### **OUTPUT VOLTAGE AND RIPPLE**

For a -2x boost:

a.) For unregulated operation when  $V_{IN} \leq \left| \frac{V_R}{2} \right|$ .

In this case, the output voltage is given by:

$$V_{OUT} = -|2V_{IN}| + I_O R_{OUT}$$
  
Equation 1.  
where R<sub>OUT</sub> =  $\frac{1}{f} \left( \frac{1}{C1} + \frac{1}{C2} \right) + \frac{R_S C2}{(C2 + C_{OUT})}$ 

Here, f is the clock frequency and  $R_S$  is the total ON resistance of the switches connecting C2 to GND and  $V_{OUT}$  in phase 2 of the charge pump operating cycle with the equivalent series resistance (ESR) of C2.

The output ripple voltage is given by:

$$V_{RIPPLE} = I_{O}R_{RIPPLE}$$
  
Equation 2.  
where R\_{RIPPLE} =  $\frac{1}{2f(C2 + C_{OUT})} + \frac{1}{2fC_{OUT}} + \frac{ESR C2}{(C2 + C_{OUT})}$ 

Here, ESR is the equivalent series resistance of C<sub>OUT</sub>.

b). For regulated operation when 
$$V_{IN} > \left| \frac{V_R}{2} \right|$$
.

In this case, the TC1142 is held in phase 2 until the output voltage drops below  $V_R$ . When this occurs, the TC1142 reverts to phase 1 for a half period of the clock, during which C2 is charged from C1. At the end of this half-period, C2 is reconnected to  $C_{OUT}$  to boost the output voltage. During the phase 1 time period, the output voltage will drop below  $V_R$  before it is boosted back, so the minimum output voltage is approximated by:

$$V_{OUT(MIN)} = -|V_R| + I_O R_{OUT}$$
  
Equation 3.  
where  $R_{OUT} = \frac{1}{2fC_{OUT}} + \frac{ESR C2}{(C2 + C_{OUT})}$ 

The output ripple voltage is given approximately by:

$$V_{\text{RIPPLE}} = \frac{(2V_{\text{IN}} - |V_{\text{R}}| + \text{ESR I}_{\text{O}}\text{C2}\left(\frac{1}{\text{C1}} + \frac{1}{\text{C2}}\right))}{\text{N}}$$
  
Equation 4.  
where N =  $\left(\frac{1}{\text{C1}} + \frac{1}{\text{C2}}\right)(\text{C2} + \text{C}_{\text{OUT}})$ 

For values of V<sub>IN</sub> higher than  $|V_R/2|$  by several hundred mV, the effect on ripple of the ESR of C<sub>OUT</sub> can be neglected compared to the "overdrive" effect of V<sub>IN</sub>.

Here, it can be seen that  $V_{\text{RIPPLE}}$  increases with increasing  $V_{\text{IN}}$ , but can be minimized by choosing small C1 and C2 values and a large  $C_{\text{OUT}}$  value.

### **CAPACITOR SELECTION**

To maintain low output impedance and ripple, it is recommended that capacitors with low equivalent series resistance (ESR) be used. Additionally, larger values of the output capacitor and smaller values of the flying capacitors will reduce output ripple. For a capacitor value of 4.7  $\mu$ F for C<sub>OUT</sub>, and values of 0.47  $\mu$ F for C1 and C2, the typical output impedance of the TC1142 in regulation is 0.5 $\Omega$ . For the capacitor ESR not to have a noticeable effect on output impedance, it should not be larger than 1/2fC<sub>OUT</sub>. This also makes its effect on ripple voltage negligible. For V<sub>IN</sub> = 3.2V and V<sub>R</sub> = -5V, the output ripple versus capacitor size for an input voltage of 3.2V and a regulated output voltage of -5V.

Surface mount ceramic capacitors are preferred for their small size, low cost, and low ESR. Low ESR tantalum capacitors also are acceptable. See Table 2 for a list of suggested capacitor suppliers.

Table 1. Vo	oltage Rip	ple vs. C1/0	C2 Flying C	apacitors
and Outpu	t Capacito	or C <sub>OUT</sub> ESF	R = 0.1Ω, I <sub>0</sub>	UT = 20 mA

C1, C2 (μF)	С <sub>оυт</sub> (µF)	V <sub>IN</sub> (V)	V <sub>OUT</sub> (V)	V <sub>RIPPLE</sub> (mV)
0.1	4.7	3.2	-5	14.6
0.22	4.7	3.2	-5	31.4
0.33	4.7	3.2	-5	46.1
0.47	4.7	3.2	-5	63.9
0.68	4.7	3.2	-5	88.7
1.0	4.7	3.2	-5	123.2
0.1	10	3.2	-5	7.0
0.22	10	3.2	-5	15.1
0.33	10	3.2	-5	22.4
0.47	10	3.2	-5	31.5
0.68	10	3.2	-5	44.7
1.0	10	3.2	-5	63.8

Manufacturer	Туре	Phone		
AVX Corp.	TPS series surface-mount tantalum	(803) 448-9411		
Matsuo	267 series surface-mount tantalum	(714) 969-2491		
Sprague	593D, 594D, 595D, series surface-mount tantalum	(207) 324-4140		
AVX Corp.	X7R type surface-mount ceramic	(803) 448-9411		
Matsuo	X7R type surface-mount ceramic	(714) 969-2491		
Murata	Ceramic chip capacitors	(800) 831-9172		
Taiyo Yuden	Ceramic chip capacitors	(800) 348-2496		
Tokin	Ceramic chip capacitors	(408) 432-8020		

# Table 2. Low ESR Surface-Mount CapacitorManufacturers

## POWER EFFICIENCY

Assuming the output is loaded with at least 20% of the maximum available output current, the power efficiency of the TC1142 can be estimated using the following equation:

Equation 5.

For example, a 3.2 Volt V<sub>IN</sub>, and a –5 Volt V<sub>R</sub> will have an efficiency of approximately 78%. For loads less than 20% of the maximum available output current, the power efficiency will be substantially reduced. Other factors that affect the actual efficiency include:

- 1) Losses from power consumed by the internal oscillator (if used).
- 2) I<sup>2</sup>R losses due to the on-resistance of the MOSFET charge pump switches.
- 3) Charge pump capacitor losses due to ESR.
- 4) Losses that occur during charge transfer (from the flying capacitors to the output capacitor) when a voltage difference exists between these capacitors.

## CHOICE OF -2X OR -1X CONNECTIONS

If required output voltage can be achieved using a -1x configuration then this is preferred for the following reasons:

- 1) Power efficiency is improved from  $V_R/2V_{IN}$  to  $V_R/V_{IN}$
- 2) Only one flying capacitor needed
- 3) The output ripple becomes proportional to  $V_{IN} V_R$  rather than 2  $V_{IN} V_R$ .

## LAYOUT CONSIDERATIONS

Proper layout is important to obtain optimal performance. Mount capacitors as close to their connecting device pins as possible to minimize stray inductance and capacitance. It is recommended that a large ground plane be used to reduce noise leakage into other circuitry.



Figure 4. Timing Diagram

### TAPING FORM



### PACKAGE DIMENSIONS





# WORLDWIDE SALES AND SERVICE

### AMERICAS

**Corporate Office** 

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: 480-792-7627 Web Address: http://www.microchip.com

**Rocky Mountain** 

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B Atlanta, GA 30350 Tel: 770-640-0034 Fax: 770-640-0307

Austin

Analog Product Sales 8303 MoPac Expressway North Suite A-201 Austin, TX 78759 Tel: 512-345-2030 Fax: 512-345-6085

Boston

2 Lan Drive, Suite 120 Westford, MA 01886 Tel: 978-692-3848 Fax: 978-692-3821

**Boston** Analog Product Sales Unit A-8-1 Millbrook Tarry Condominium

97 Lowell Road Concord, MA 01742 Tel: 978-371-6400 Fax: 978-371-0050

Chicago

333 Pierce Road, Suite 180 Itasca, IL 60143 Tel: 630-285-0071 Fax: 630-285-0075 Dallas

4570 Westgrove Drive, Suite 160 Addison, TX 75001 Tel: 972-818-7423 Fax: 972-818-2924

Dayton Two Prestige Place, Suite 130 Miamisburg, OH 45342 Tel: 937-291-1654 Fax: 937-291-9175

Detroit

Tri-Atria Office Building 32255 Northwestern Highway, Suite 190 Farmington Hills, MI 48334 Tel: 248-538-2250 Fax: 248-538-2260

Los Angeles

18201 Von Karman, Suite 1090 Irvine, CA 92612 Tel: 949-263-1888 Fax: 949-263-1338

### **Mountain View**

Analog Product Sales 1300 Terra Bella Avenue Mountain View, CA 94043-1836 Tel: 650-968-9241 Fax: 650-967-1590

#### New York

150 Motor Parkway, Suite 202 Hauppauge, NY 11788 Tel: 631-273-5305 Fax: 631-273-5335

San Jose Microchip Technology Inc. 2107 North First Street, Suite 590 San Jose, CA 95131 Tel: 408-436-7950 Fax: 408-436-7955

Toronto 6285 Northam Drive, Suite 108 Mississauga, Ontario L4V 1X5, Canada Tel: 905-673-0699 Fax: 905-673-6509

### ASIA/PACIFIC

China - Beijing Microchip Technology Beijing Office Unit 915 New China Hong Kong Manhattan Bldg. No. 6 Chaoyangmen Beidajie Beijing, 100027, No. China Tel: 86-10-85282100 Fax: 86-10-85282104 China - Shanghai Microchip Technology Shanghai Office Room 701, Bldg. B Far East International Plaza No. 317 Xian Xia Road Shanghai, 200051 Tel: 86-21-6275-5700 Fax: 86-21-6275-5060 Hong Kong Microchip Asia Pacific RM 2101, Tower 2, Metroplaza 223 Hing Fong Road Kwai Fong, N.T., Hong Kong Tel: 852-2401-1200 Fax: 852-2401-3431 India Microchip Technology Inc. India Liaison Office

Divyasree Chambers 1 Floor, Wing A (A3/A4) No. 11, OíShaugnessey Road Bangalore, 560 025, India Tel: 91-80-2290061 Fax: 91-80-2290062 Japan Microchip Technology Intl. Inc. Benex S-1 6F 3-18-20, Shinyokohama Kohoku-Ku, Yokohama-shi Kanagawa, 222-0033, Japan Tel: 81-45-471- 6166 Fax: 81-45-471-6122 Korea Microchip Technology Korea 168-1, Youngbo Bldg. 3 Floor Samsung-Dong, Kangnam-Ku

Seoul, Korea Tel: 82-2-554-7200 Fax: 82-2-558-5934

### ASIA/PACIFIC (continued)

Singapore

Microchip Technology Singapore Pte Ltd. 200 Middle Road #07-02 Prime Centre Singapore, 188980 Tel: 65-334-8870 Fax: 65-334-8850 Taiwan Microchip Technology Taiwan 11F-3, No. 207 Tung Hua North Road Taipei, 105, Taiwan Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

### **EUROPE**

Australia Microchip Technology Australia Pty Ltd Suite 22, 41 Rawson Street Epping 2121, NSW Australia Tel: 61-2-9868-6733 Fax: 61-2-9868-6755 Denmark Microchip Technology Denmark ApS Regus Business Centre Lautrup hoj 1-3 Ballerup DK-2750 Denmark Tel: 45 4420 9895 Fax: 45 4420 9910 France Arizona Microchip Technology SARL Parc díActivite du Moulin de Massy 43 Rue du Saule Trapu Batiment A - ler Etage 91300 Massy, France Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79 Germany Arizona Microchip Technology GmbH Gustav-Heinemann Ring 125 D-81739 Munich, Germany Tel: 49-89-627-144 0 Fax: 49-89-627-144-44 Germany Analog Product Sales Lochhamer Strasse 13 D-82152 Martinsried, Germany Tel: 49-89-895650-0 Fax: 49-89-895650-22 Italy Arizona Microchip Technology SRL Centro Direzionale Colleoni Palazzo Taurus 1 V. Le Colleoni 1 20041 Agrate Brianza Milan, Italy Tel: 39-039-65791-1 Fax: 39-039-6899883 United Kingdom Arizona Microchip Technology Ltd. 505 Eskdale Road Winnersh Triangle Wokingham Berkshire, England RG41 5TU Tel: 44 118 921 5869 Fax: 44-118 921-5820

All rights reserved. © 2001 Microchip Technology Incorporated. Printed in the USA. 1/01 Printed on recycled paper.

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, except as maybe explicitly expressed herein, under any intellec-tual property rights. The Microchip logo and name are registered trademarks of Microchip Technology Inc. in the U.S.A. and other countries. All rights reserved. All other trademarks mentioned herein are the property of their respective companies.

01/09/01